

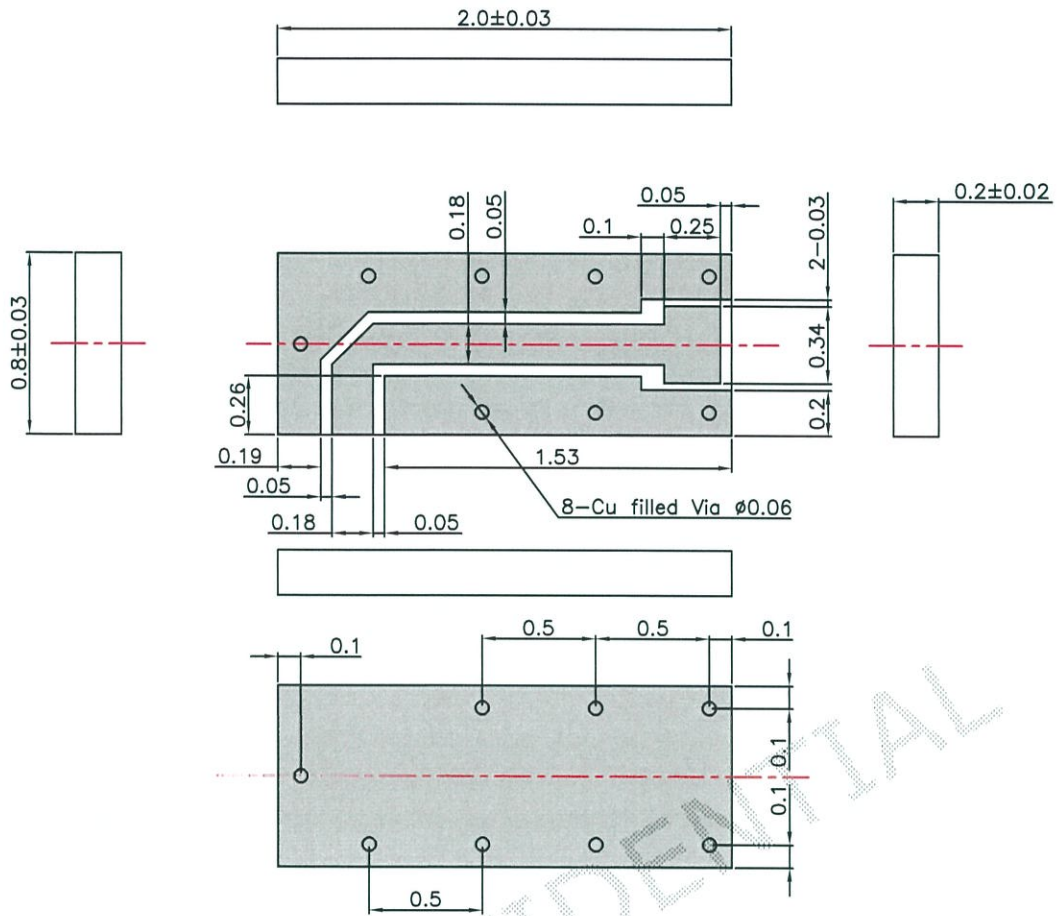
Notes.

1. Surface roughness : $Ra \leq 0.05\mu m$
2. Thin film metallization
 - AREA Ti : $0.1\mu m \pm 0.02\mu m$
 - Pt : $0.2\mu m \pm 0.04\mu m$
 - Au : $1.0\mu m \pm 0.2\mu m$
3. Inspection of surface quality
 - 1) Crack/Chipping : $< 50\mu m$
 - 2) Burr of Metallize : $< 30\mu m$
 - 3) Scratch : Width $< 20\mu m$
 - 4) Island : $< 30\mu m$

The NG product is marked with black ink.
4. Characteristic
 - No peeling off and color changing, blistering after baking at $350^\circ C/3min$.
 - Strength by Au- $\phi 25\mu m$ wire-bond test $\geq 4gf$
5. Packing form
 - 1) Sheet : D-174A(UV TAPE)
 - 2) Wafer SIZE: 4inch Square

General tolerance : ± 0.02

REV	DATE	DSGN	CHECK	APPR	DESCRIPTION	MATERIAL	FINISH	NOTE
						Quartz		
	DATE	DESIGNED	DRAWN	CHECKED	APPR'D	TITLE		
	'20.09.21	HS.KIM	HS.KIM	J.Y.J	T.M.ya	Glass TGV(Submount)		
KOREA SHINKO MICROELECTRONICS CO.,LTD.						PROJ 3RD ANGLE	SCALE 30:1	DRAWING NO. KHX1348-a



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						3RD	30:1	KHX1348-b
						ANGLE		